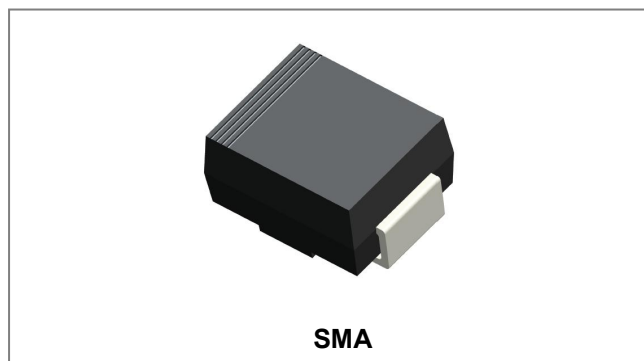


## SK26A SCHOTTKY RECTIFIER



### Features

- Small foot print, surface mountable
- Very low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Green products in compliance the ROHS directive
- This is a Pb - Free device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram



### Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

### Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	-	60	V
Average Rectified Forward Current	$I_F (AV)$	50% duty cycle @ $T_C = 105^\circ\text{C}$ , rectangular wave form	2	A
Peak One Cycle Non-Repetitive Surge Current	$I_{FSM}$	8.3ms, Half Sine pulse, $T_c = 25^\circ\text{C}$	50	A

### Electrical Characteristics:

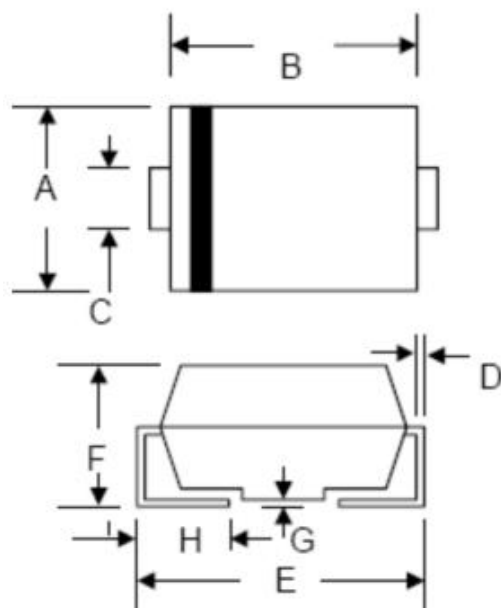
Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	$V_{F1}$	@ 2A, Pulse, $T_J = 25^\circ\text{C}$	0.68	0.7	V
Reverse Current*	$I_{R1}$	@ $V_R = \text{rated } V_R$ , $T_J = 25^\circ\text{C}$	0.007	1.0	mA
	$I_{R2}$	@ $V_R = \text{rated } V_R$ , $T_J = 100^\circ\text{C}$	5	20	mA
Junction Capacitance	$C_T$	@ $V_R = 5\text{V}$ , $T_C = 25^\circ\text{C}$ , $f_{SIG} = 1\text{MHz}$	160	250	pF
Series Inductance	$L_S$	Measured lead to lead 5 mm from package body	8.0	-	nH
Voltage Rate of Change	$dv/dt$	-	-	10,000	V/ $\mu\text{s}$

\* Pulse width < 300  $\mu\text{s}$ , duty cycle < 2%

## Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	$T_J$	-	-55 to +150	°C
Storage Temperature	$T_{stg}$	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case	$R_{\theta Jc}$	DC operation	8	°C/W
Approximate Weight	wt	-	0.06	g

## Mechanical Dimensions SMA



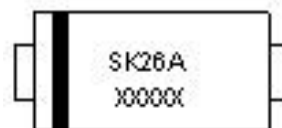
SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.40	2.84	0.094	0.112
B	3.99	4.75	0.157	0.187
C	1.05	1.70	0.041	0.067
D	0.15	0.51	0.006	0.020
E	4.80	5.66	0.189	0.223
F	1.90	2.95	0.075	0.116
G	0.05	0.203	0.002	0.008
H	0.76	1.52	0.030	0.600

## Ordering Information

Device	Package	Shipping
SK26A	SMA	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

## Marking Diagram



Where XXXXX is YYWWL

SK = Device Type  
2 = Forward Current (2A)  
6 = Reverse Voltage (60V)  
A = Package type  
YY = Year  
WW = Week  
L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

## Ratings and Characteristics Curves

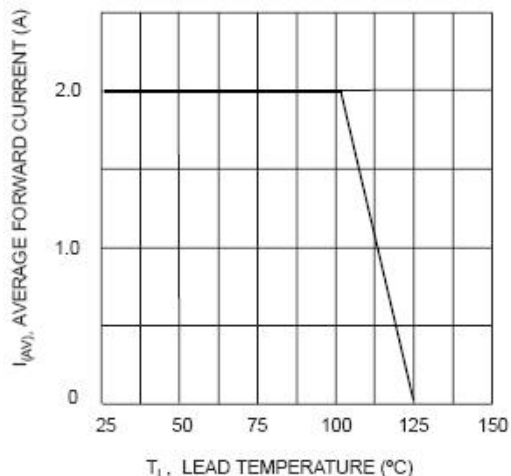


Fig. 1 Forward Current Derating Curve

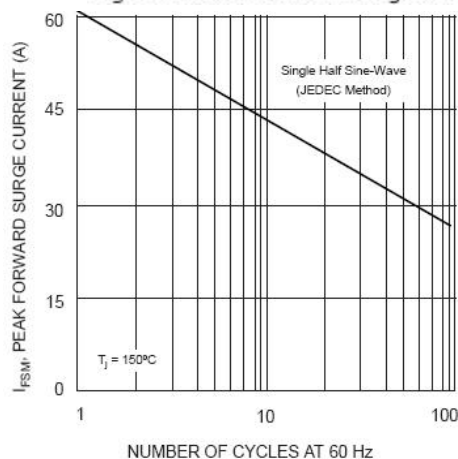


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

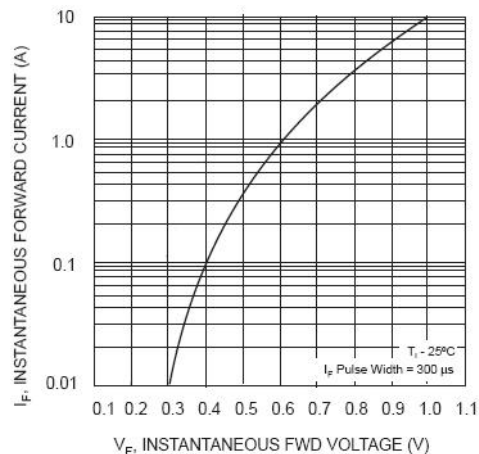


Fig. 2 Typ. Forward Characteristics

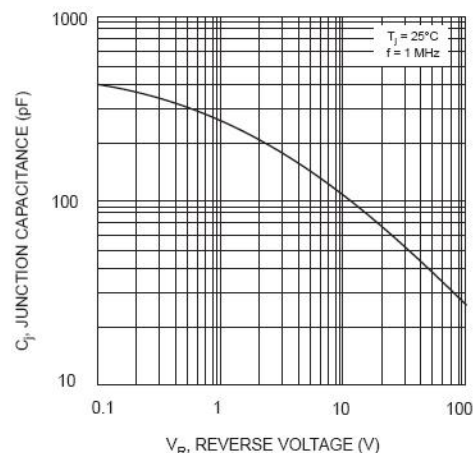


Fig. 4 Typical Junction Capacitance

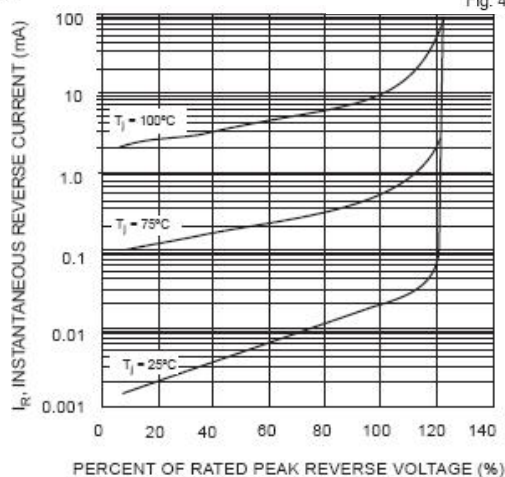
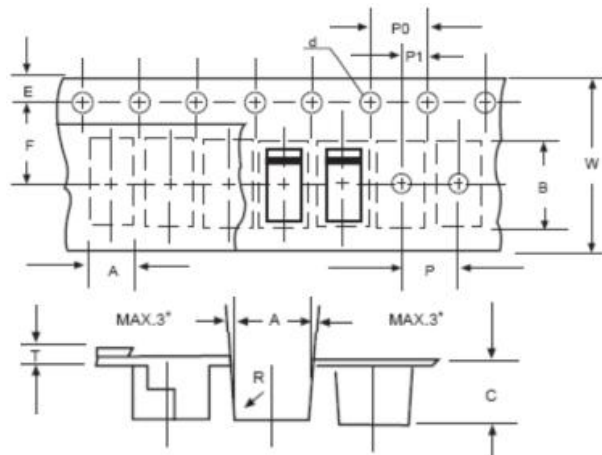


Fig. 5 Typical Reverse Characteristics

## Carrier Tape Specification SMA



SYMBOL	Millimeters	
	Min.	Max.
A	2.97	3.17
B	5.70	5.90
C	2.32	2.52
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
T	0.25	0.35
W	11.80	12.20

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